

Notes in handling CSSOCKET and BSSOCKET

Please read Chapter I and II in the "Technical information" from below URL before you mount CSSOCKET or BSSOCKET on PWB.

- 1.) CSSOCKET and BSSOCKET were developed for the emulation test or system development purpose only. Therefore, Electrical Appliance and Material Safety Law or EMI standards do not approve the adapter.
- 2.) While a packing box has been kept under ambient temperature higher than 50 for long time, the box might be deformed. The storage place should be free from sunlight, and room temperature should be 40 or lower.
- 3.) To prevent the solder balls from oxidation, BSSOCKET is packed in a vacuum plastic bag. BSSOCKET should be soldered onto a target board within the same day after opening the bag. Keep it in a dissector if BSSOCKET is soldered on the following day.
- 4.) Polyamide protection films covers on the top of BSSOCKET to protect the contact pins from fling flux during solder process. The cover should not be taken away until reflow soldering is finished.
- 5.) Recommending reflow temperature profile for CSSOCKET and BSSOCKET
Process Temperature:
Preheating 150 to 180 for about 180 seconds
Soldering 210 or higher for 30 to 60 seconds (Sn - Pb)
- 6.) Refer to the product drawings for the recommending soldering footprints.
- 7.) Cleaning for CSSOCKET and BSSOCKET should not be done. The cleaning materials and flux will contaminate in the sockets due to the construction of the socket. Cleaning for DIP components should not be done with the sockets since flux for soldering DIP components will penetrate into the socket.
- 8.) After soldering, guide pins of CSSOCKET or BSSOCKET should be soldered at the PWB rear side, or the sockets should be fixed to PWB with a hardening resin to increase physical strength.
- 9.) When the sockets are used for increasing height between LSPACK and CSSOCKET or BSSOCKET. The multitasking CSSOCKET should be used.
- 10.) CSSOCKET and BSSOCKET should be used for emulation test purpose only.
- 11.) CSSOCKET and BSSOCKET cannot withstand under vibration or shock environment.